

Package Drawings

[XAPP415: Thermal Packaging Management Application Note \(v1.0\) 12/19/01](#)

[XAPP425: Solder Reflow Guidelines for BGA Application Note \(v1.0\) 12/9/02](#)

[XAPP426: Flip Chip Implementation Guidelines Application Note \(v1.0\) 12/9/02](#)

Package Information

This section contains the following information:

Introduction to Xilinx Packaging

Package Technology Briefs

Inches and Millimeters

Dimensions for Xilinx Quad Flat Packs

Suggested Board Layout of Soldered Pads for BGA Packages

Recommended PCB Design Rules

Cavity Up or Cavity Down

Pressure Handling Capacity

Clockwise or Counterclockwise

Summary of Thermal Resistance for Packages

Package Electrical Characterization

This section contains the following information:

Theoretical Background

Analytical Formulas for Lead Inductance

General Measurement Procedure

Data Acquisition and Package Electrical Database

Component Mass (Weight) by Package Type

Thermally Enhanced Packaging

This section contains the following information:

The Package Offering

Overview

Where and When Offered

Mass Comparison

Thermal Data for the HQ

Moisture Sensitivity of PSMCs

This section contains the following information:

- Moisture Induced Cracking During Solder Reflow
 - Package Moisture Sensitivity Levels per J-STD-020
 - Factory Floor Life
 - Dry Bake Recommendation and Dry Bag Policy
 - Handling Parts in Sealed Bags
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Tape and Reel

This section contains the following information:

- Benefits
 - Cover Tape
 - Reel
 - Bar Code Label
 - Shipping Box
 - Tape and Reel Packaging
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Reflow Soldering Process Guidelines

This section contains the following information:

- Solder Reflow Process
 - Soldering Problems Summary
 - Typical Conditions for IR Reflow
 - Typical Conditions for Vapor Phase Reflow Soldering
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Sockets

This section contains the following information:

- Socket Manufacturers
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